

can change or modify the embodiments without departing from the scope and spirit of the present invention.

**What is claimed is:**

1. An exhaust valve for semiconductor manufacturing process, comprising:

5 a valve body having a chamber formed at the center thereof and exhaust ports formed at left and right sides thereof and connected to treatment devices respectively;

a rotary cylinder rotatably coupled to the chamber of the valve body, the rotary cylinder having an inlet formed in the  
10 lower portion thereof for entrance of exhaust gas, an opening formed at a side thereof and communicating with the inlet so as to selectively open and close the exhaust ports, and a shaft portion formed on the upper portion thereof;

a protective cover coupled to the outer circumferential  
15 surface of the rotary cylinder;

an exhaust guide member coupled to the lower portion of the valve body for guiding exhaust gas discharged from a vacuum pump to the inlet of the rotary cylinder;

an adapter seated on the upper portion of the valve body  
20 and surrounding the shaft portion of the rotary cylinder;

an actuator coupled to the upper portion of the adapter for rotating the rotary cylinder in right and left directions; and

sensing means mounted at the upper portion of the valve body for sensing the opening position of the exhaust ports,

characterized in that a first sealing member is mounted between the rotary cylinder and the protective cover.

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2. The exhaust valve for semiconductor manufacturing process according to claim 1, wherein a second sealing member is mounted between the chamber of the valve body and the outer circumferential surface of the protective cover.

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3. The exhaust valve for semiconductor manufacturing process according to claim 1 or 2, wherein the first and second sealing members are O-rings.